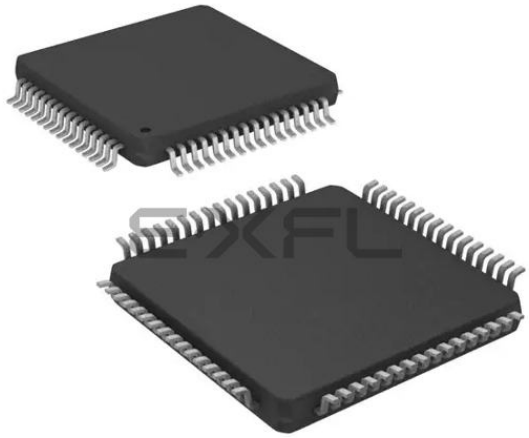

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	100MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	49
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 28x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx430f064ht-i-pt

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TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number			Pin Type	Buffer Type	Description
	64-pin QFN/ TQFP	100-pin TQFP	124-pin VTLA			
RB0	16	25	B14	I/O	ST	PORTB is a bidirectional I/O port
RB1	15	24	A15	I/O	ST	
RB2	14	23	B13	I/O	ST	
RB3	13	22	A13	I/O	ST	
RB4	12	21	B11	I/O	ST	
RB5	11	20	A12	I/O	ST	
RB6	17	26	A20	I/O	ST	
RB7	18	27	B16	I/O	ST	
RB8	21	32	A23	I/O	ST	
RB9	22	33	B19	I/O	ST	
RB10	23	34	A24	I/O	ST	
RB11	24	35	B20	I/O	ST	
RB12	27	41	B23	I/O	ST	
RB13	28	42	A28	I/O	ST	
RB14	29	43	B24	I/O	ST	
RB15	30	44	A29	I/O	ST	
RC1	—	6	A5	I/O	ST	PORTC is a bidirectional I/O port
RC2	—	7	B4	I/O	ST	
RC3	—	8	A6	I/O	ST	
RC4	—	9	B5	I/O	ST	
RC12	39	63	B34	I/O	ST	
RC13	47	73	A47	I/O	ST	
RC14	48	74	B40	I/O	ST	
RC15	40	64	A42	I/O	ST	
RD0	46	72	B39	I/O	ST	PORTD is a bidirectional I/O port
RD1	49	76	A52	I/O	ST	
RD2	50	77	B42	I/O	ST	
RD3	51	78	A53	I/O	ST	
RD4	52	81	B44	I/O	ST	
RD5	53	82	A55	I/O	ST	
RD6	54	83	B45	I/O	ST	
RD7	55	84	A56	I/O	ST	
RD8	42	68	B37	I/O	ST	
RD9	43	69	A45	I/O	ST	
RD10	44	70	B38	I/O	ST	
RD11	45	71	A46	I/O	ST	
RD12	—	79	B43	I/O	ST	
RD13	—	80	A54	I/O	ST	
RD14	—	47	B26	I/O	ST	
RD15	—	48	A31	I/O	ST	

Legend: CMOS = CMOS compatible input or output; Analog = Analog input; P = Power
ST = Schmitt Trigger input with CMOS levels; O = Output; I = Input
TTL = TTL input buffer

Note 1: This pin is only available on devices without a USB module.
2: This pin is only available on devices with a USB module.
3: This pin is not available on 64-pin devices.

TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number			Pin Type	Buffer Type	Description
	64-pin QFN/ TQFP	100-pin TQFP	124-pin VTLA			
CVREF-	15	28	A21	I	Analog	Comparator Voltage Reference (Low)
CVREF+	16	29	B17	I	Analog	Comparator Voltage Reference (High)
CVREFOUT	23	34	A24	I	Analog	Comparator Voltage Reference (Output)
C1INA	11	20	A12	I	Analog	Comparator 1 Inputs
C1INB	12	21	B11	I	Analog	
C1INC	5	11	B6	I	Analog	
C1IND	4	10	A7	I	Analog	
C2INA	13	22	A13	I	Analog	Comparator 2 Inputs
C2INB	14	23	B13	I	Analog	
C2INC	8	14	A9	I	Analog	
C2IND	6	12	A8	I	Analog	
C1OUT	PPS	PPS	PPS	O	—	Comparator 1 Output
C2OUT	PPS	PPS	PPS	O	—	Comparator 2 Output
PMALL	30	44	A29	O	TTL/ST	Parallel Master Port Address Latch Enable Low Byte
PMALH	29	43	B24	O	TTL/ST	Parallel Master Port Address Latch Enable High Byte
PMA0	30	44	A29	O	TTL/ST	Parallel Master Port Address bit 0 Input (Buffered Slave modes) and Output (Master modes)
PMA1	29	43	B24	O	TTL/ST	Parallel Master Port Address bit 0 Input (Buffered Slave modes) and Output (Master modes)
PMA2	8	14	A9	O	TTL/ST	Parallel Master Port data (Demultiplexed Master mode) or Address/Data (Multiplexed Master modes)
PMA3	6	12	A8	O	TTL/ST	
PMA4	5	11	B6	O	TTL/ST	
PMA5	4	10	A7	O	TTL/ST	
PMA6	16	29	B17	O	TTL/ST	
PMA7	22	28	A21	O	TTL/ST	
PMA8	32	50	A32	O	TTL/ST	
PMA9	31	49	B27	O	TTL/ST	
PMA10	28	42	A28	O	TTL/ST	
PMA11	27	41	B23	O	TTL/ST	
PMA12	24	35	B20	O	TTL/ST	
PMA13	23	34	A24	O	TTL/ST	
PMA14	45	71	A46	O	TTL/ST	
PMA15	44	70	B38	O	TTL/ST	
PMCS1	45	71	A46	O	TTL/ST	
PMCS2	44	70	B38	O	TTL/ST	
PMD0	60	93	B52	I/O	TTL/ST	
PMD1	61	94	A64	I/O	TTL/ST	
PMD2	62	98	A66	I/O	TTL/ST	

Legend: CMOS = CMOS compatible input or output
ST = Schmitt Trigger input with CMOS levels
TTL = TTL input buffer
Analog = Analog input
O = Output
P = Power
I = Input

Note 1: This pin is only available on devices without a USB module.
2: This pin is only available on devices with a USB module.
3: This pin is not available on 64-pin devices.

3.2 Architecture Overview

The MIPS32® M4K® processor core contains several logic blocks working together in parallel, providing an efficient high-performance computing engine. The following blocks are included with the core:

- Execution Unit
- Multiply/Divide Unit (MDU)
- System Control Coprocessor (CP0)
- Fixed Mapping Translation (FMT)
- Dual Internal Bus interfaces
- Power Management
- MIPS16e® Support
- Enhanced JTAG (EJTAG) Controller

3.2.1 EXECUTION UNIT

The MIPS32® M4K® processor core execution unit implements a load/store architecture with single-cycle ALU operations (logical, shift, add, subtract) and an autonomous multiply/divide unit. The core contains thirty-two 32-bit General Purpose Registers (GPRs) used for integer operations and address calculation. One additional register file shadow set (containing thirty-two registers) is added to minimize context switching overhead during interrupt/exception processing. The register file consists of two read ports and one write port and is fully bypassed to minimize operation latency in the pipeline.

The execution unit includes:

- 32-bit adder used for calculating the data address
- Address unit for calculating the next instruction address
- Logic for branch determination and branch target address calculation
- Load aligner
- Bypass multiplexers used to avoid stalls when executing instruction streams where data producing instructions are followed closely by consumers of their results
- Leading Zero/One detect unit for implementing the `CLZ` and `CLO` instructions
- Arithmetic Logic Unit (ALU) for performing bitwise logical operations
- Shifter and store aligner

3.2.2 MULTIPLY/DIVIDE UNIT (MDU)

The MIPS32® M4K® processor core includes a Multiply/Divide Unit (MDU) that contains a separate pipeline for multiply and divide operations. This pipeline operates in parallel with the Integer Unit (IU) pipeline and does not stall when the IU pipeline stalls. This allows MDU operations to be partially masked by system stalls and/or other integer unit instructions.

The high-performance MDU consists of a 32x16 booth recoded multiplier, result/accumulation registers (HI and LO), a divide state machine, and the necessary multiplexers and control logic. The first number shown ('32' of 32x16) represents the *rs* operand. The second number ('16' of 32x16) represents the *rt* operand. The PIC32 core only checks the value of the latter (*rt)* operand to determine how many times the operation must pass through the multiplier. The 16x16 and 32x16 operations pass through the multiplier once. A 32x32 operation passes through the multiplier twice.

The MDU supports execution of one 16x16 or 32x16 multiply operation every clock cycle; 32x32 multiply operations can be issued every other clock cycle. Appropriate interlocks are implemented to stall the issuance of back-to-back 32x32 multiply operations. The multiply operand size is automatically determined by logic built into the MDU.

Divide operations are implemented with a simple 1 bit per clock iterative algorithm. An early-in detection checks the sign extension of the dividend (*rs*) operand. If *rs* is 8 bits wide, 23 iterations are skipped. For a 16-bit wide *rs*, 15 iterations are skipped and for a 24-bit wide *rs*, 7 iterations are skipped. Any attempt to issue a subsequent `MDU` instruction while a divide is still active causes an IU pipeline stall until the divide operation is completed.

Table 3-1 lists the repeat rate (peak issue rate of cycles until the operation can be reissued) and latency (number of cycles until a result is available) for the PIC32 core multiply and divide instructions. The approximate latency and repeat rates are listed in terms of pipeline clocks.

TABLE 3-1: MIPS32® M4K® PROCESSOR CORE HIGH-PERFORMANCE INTEGER MULTIPLY/ DIVIDE UNIT LATENCIES AND REPEAT RATES

Op code	Operand Size (mul *rt*) (div *rs*)	Latency	Repeat Rate
`MULT/MULTU, MADD/MADDU, MSUB/MSUBU`	16 bits	1	1
	32 bits	2	2
`MUL`	16 bits	2	1
	32 bits	3	2
`DIV/DIVU`	8 bits	12	11
	16 bits	19	18
	24 bits	26	25
	32 bits	33	32

7.0 INTERRUPT CONTROLLER

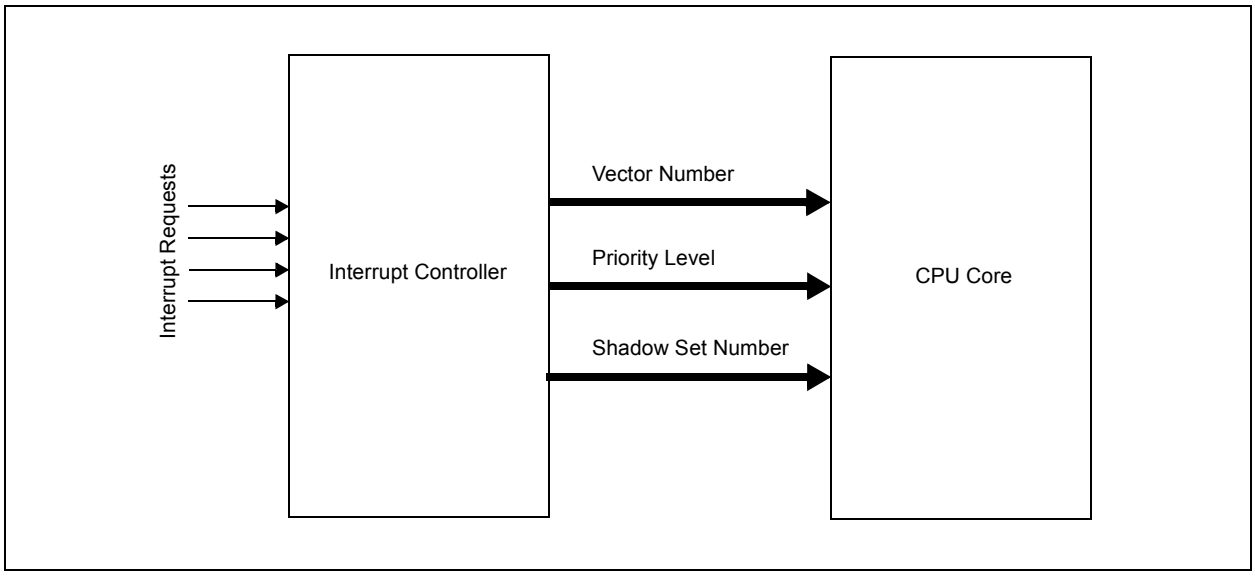
Note: This data sheet summarizes the features of the PIC32MX330/350/370/430/450/470 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 8. "Interrupt Controller"** (DS60001108), which is available from the *Documentation* > *Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

PIC32MX330/350/370/430/450/470 devices generate interrupt requests in response to interrupt events from peripheral modules. The interrupt control module exists externally to the CPU logic and prioritizes the interrupt events before presenting them to the CPU.

The PIC32MX330/350/370/430/450/470 interrupt module includes the following features:

- Up to 76 interrupt sources
- Up to 46 interrupt vectors
- Single and multi-vector mode operations
- Five external interrupts with edge polarity control
- Interrupt proximity timer
- Seven user-selectable priority levels for each vector
- Four user-selectable subpriority levels within each priority
- Dedicated shadow set configurable for any priority level (see the FSRSSEL<2:0> bits (DEVCFG3<18:16>) in **28.0 "Special Features"** for more information)
- Software can generate any interrupt
- User-configurable interrupt vector table location
- User-configurable interrupt vector spacing

FIGURE 7-1: INTERRUPT CONTROLLER MODULE BLOCK DIAGRAM



8.1 Oscillator Control Registers

TABLE 8-1: OSCILLATOR CONTROL REGISTER MAP

Virtual Address (BF80_#)	Register Name(1)	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
F000	OSCCON	31:16	—	—	PLLODIV<2:0>			FRCDIV<2:0>			—	SOSCRDY	PBDIVRDY	PBDIV<1:0>		PLLMULT<2:0>			x1xx(2)
		15:0	—	COSC<2:0>			—	NOSC<2:0>			CLKLOCK	ULOCK(4)	SLOCK	SLPEN	CF	UFRCEN(4)	SOSCEN	OSWEN	xxxx(2)
F010	OSCTUN	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	TUN<5:0>						0000
F020	REFOCON	31:16	—	RODIV<14:0>															0000
		15:0	ON	—	SIDL	OE	RSLP	—	DIVSWEN	ACTIVE	—	—	—	—	ROSEL<3:0>				0000
F030	REFOTRIM	31:16	ROTRIM<8:0>									—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.2 "CLR, SET, and INV Registers"** for more information.

2: Reset values are dependent on the DEVCFGx Configuration bits and the type of reset.

3: This bit is only available on devices with a USB module.

9.0 PREFETCH CACHE

Note: This data sheet summarizes the features of the PIC32MX330/350/370/430/450/470 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 4. "Prefetch Cache"** (DS60001119), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

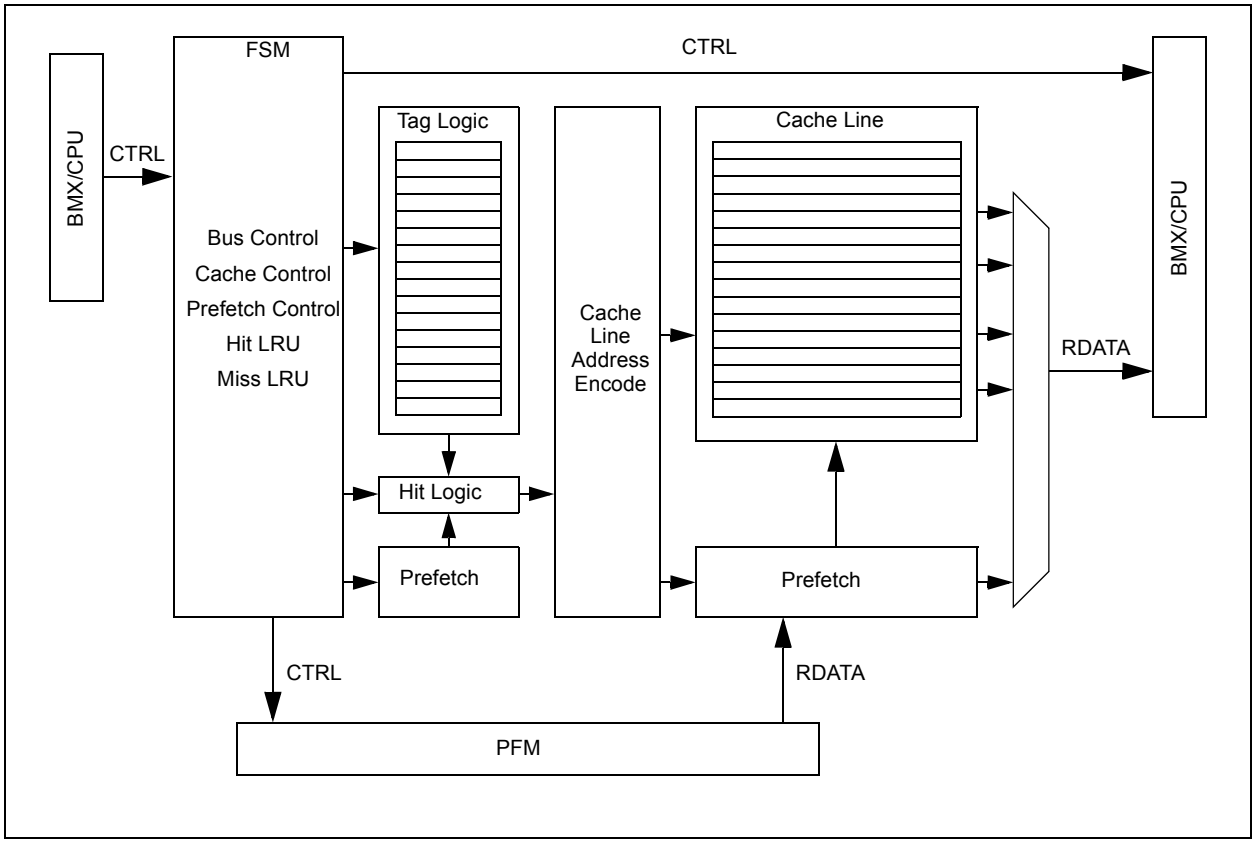
Prefetch cache increases performance for applications executing out of the cacheable program Flash memory regions by implementing instruction caching, constant data caching and instruction prefetching.

9.1 Features

- 16 fully associative lockable cache lines
- 16-byte cache lines
- Up to four cache lines allocated to data
- Two cache lines with address mask to hold repeated instructions
- Pseudo LRU replacement policy
- All cache lines are software writable
- 16-byte parallel memory fetch
- Predictive instruction prefetch

A simplified block diagram of the Prefetch Cache module is illustrated in Figure 9-1.

FIGURE 9-1: PREFETCH CACHE MODULE BLOCK DIAGRAM



REGISTER 10-12: DCHxSSIZ: DMA CHANNEL 'x' SOURCE SIZE REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CHSSIZ<15:8>							
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CHSSIZ<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15-0 **CHSSIZ<15:0>:** Channel Source Size bits

1111111111111111 = 65,535 byte source size
.
.
.
0000000000000010 = 2 byte source size
0000000000000001 = 1 byte source size
0000000000000000 = 65,536 byte source size

REGISTER 10-13: DCHxDSIZ: DMA CHANNEL 'x' DESTINATION SIZE REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CHDSIZ<15:8>							
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CHDSIZ<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15-0 **CHDSIZ<15:0>:** Channel Destination Size bits

1111111111111111 = 65,535 byte destination size
.
.
.
0000000000000010 = 2 byte destination size
0000000000000001 = 1 byte destination size
0000000000000000 = 65,536 byte destination size

14.0 TIMER2/3, TIMER4/5

Note: This data sheet summarizes the features of the PIC32MX330/350/370/430/450/470 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 14. "Timers"** (DS60001105), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

The PIC32MX330/350/370/430/450/470 family of devices features four synchronous 16-bit timers (default) that can operate as a free-running interval timer for various timing applications and counting external events. The following modes are supported:

- Synchronous internal 16-bit timer
- Synchronous internal 16-bit gated timer
- Synchronous external 16-bit timer

Two 32-bit synchronous timers are available by combining Timer2 with Timer3 and Timer4 with Timer5. The 32-bit timers can operate in three modes:

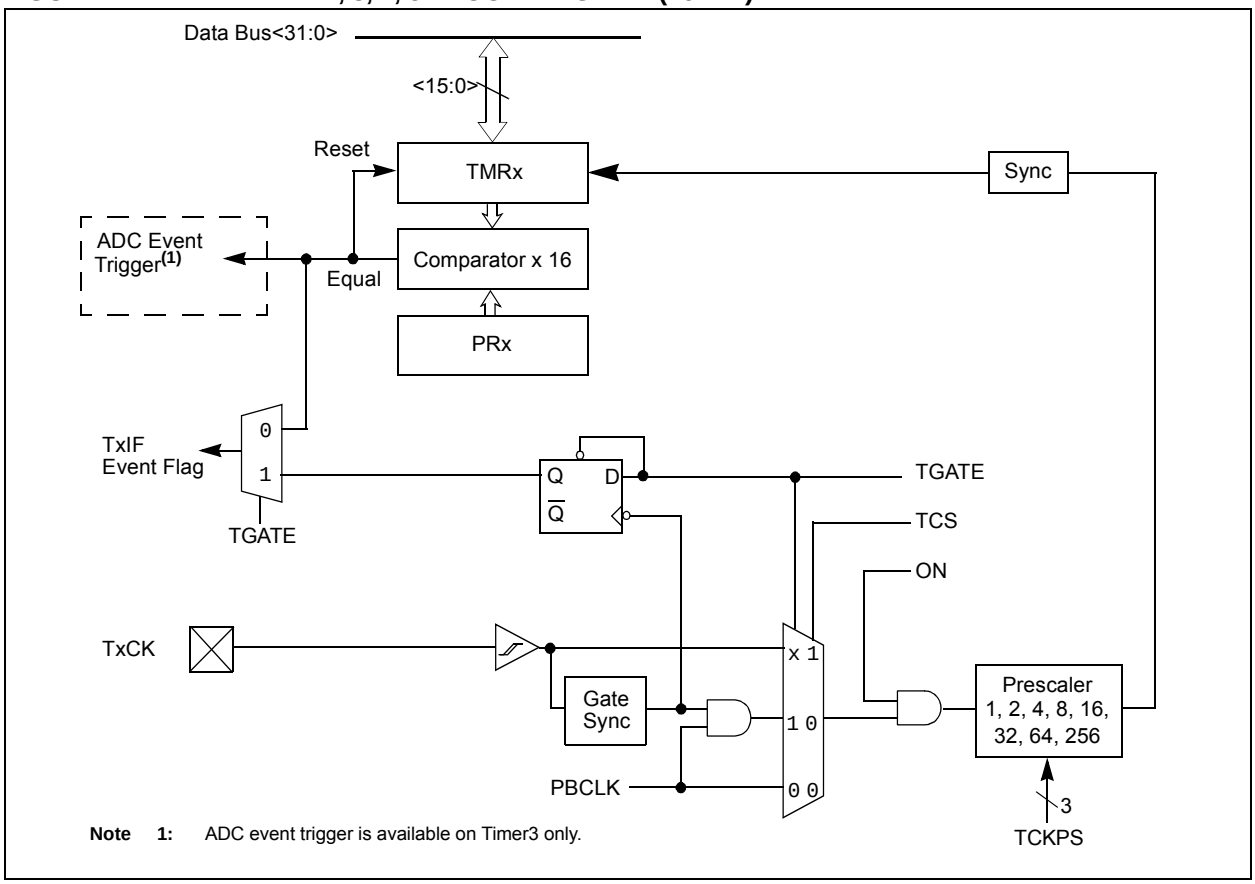
- Synchronous internal 32-bit timer
- Synchronous internal 32-bit gated timer
- Synchronous external 32-bit timer

Note: In this chapter, references to registers, TxCON, TMRx and PRx, use 'x' to represent Timer2 through 5 in 16-bit modes. In 32-bit modes, 'x' represents Timer2 or 4; 'y' represents Timer3 or 5.

14.1 Additional Supported Features

- Selectable clock prescaler
- Timers operational during CPU idle
- Time base for Input Capture and Output Compare modules (Timer2 and Timer3 only)
- ADC event trigger (Timer3 in 16-bit mode, Timer2/3 in 32-bit mode)
- Fast bit manipulation using CLR, SET, and INV registers

FIGURE 14-1: TIMER2, 3, 4, 5 BLOCK DIAGRAM (16-BIT)



Note 1: ADC event trigger is available on Timer3 only.

REGISTER 20-2: UxSTA: UARTx STATUS AND CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0
	—	—	—	—	—	—	—	ADM_EN
23:16	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	ADDR<7:0>							
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R-0	R-1
	UTXISEL<1:0>		UTXINV	URXEN	UTXBRK	UTXEN	UTXBF	TRMT
7:0	R/W-0	R/W-0	R/W-0	R-1	R-0	R-0	R/W-0	R-0
	URXISEL<1:0>		ADDEN	RIDLE	PERR	FERR	OERR	URXDA

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-25 **Unimplemented:** Read as '0'

bit 24 **ADM_EN:** Automatic Address Detect Mode Enable bit
- 1 = Automatic Address Detect mode is enabled
- 0 = Automatic Address Detect mode is disabled

bit 23-16 **ADDR<7:0>:** Automatic Address Mask bits

When the ADM_EN bit is '1', this value defines the address character to use for automatic address detection.

bit 15-14 **UTXISEL<1:0>:** TX Interrupt Mode Selection bits
- 11 = Reserved, do not use
- 10 = Interrupt is generated and asserted while the transmit buffer is empty
- 01 = Interrupt is generated and asserted when all characters have been transmitted
- 00 = Interrupt is generated and asserted while the transmit buffer contains at least one empty space

bit 13 **UTXINV:** Transmit Polarity Inversion bit

If IrDA mode is disabled (i.e., IREN (UxMODE<12>) is '0'):
- 1 = UxTX Idle state is '0'
- 0 = UxTX Idle state is '1'

If IrDA mode is enabled (i.e., IREN (UxMODE<12>) is '1'):
- 1 = IrDA encoded UxTX Idle state is '1'
- 0 = IrDA encoded UxTX Idle state is '0'

bit 12 **URXEN:** Receiver Enable bit
- 1 = UARTx receiver is enabled. UxRX pin is controlled by UARTx (if ON = 1)
- 0 = UARTx receiver is disabled. UxRX pin is ignored by the UARTx module. UxRX pin is controlled by the port.

bit 11 **UTXBRK:** Transmit Break bit
- 1 = Send Break on next transmission. Start bit followed by twelve '0' bits, followed by Stop bit; cleared by hardware upon completion
- 0 = Break transmission is disabled or completed

bit 10 **UTXEN:** Transmit Enable bit
- 1 = UARTx transmitter is enabled. UxTX pin is controlled by UARTx (if ON = 1)
- 0 = UARTx transmitter is disabled. Any pending transmission is aborted and buffer is reset. UxTX pin is controlled by the port.

bit 9 **UTXBF:** Transmit Buffer Full Status bit (read-only)
- 1 = Transmit buffer is full
- 0 = Transmit buffer is not full, at least one more character can be written

REGISTER 21-2: PMMODE: PARALLEL PORT MODE REGISTER (CONTINUED)

bit 5-2 **WAITM<3:0>:** Data Read/Write Strobe Wait States bits(1)

1111 = Wait of 16 TPB
•
•
•
0001 = Wait of 2 TPB
0000 = Wait of 1 TPB (default)

bit 1-0 **WAITE<1:0>:** Data Hold After Read/Write Strobe Wait States bits(1)

11 = Wait of 4 TPB
10 = Wait of 3 TPB
01 = Wait of 2 TPB
00 = Wait of 1 TPB (default)

For Read operations:
11 = Wait of 3 TPB
10 = Wait of 2 TPB
01 = Wait of 1 TPB
00 = Wait of 0 TPB (default)

Note 1: Whenever WAITM<3:0> = 0000, WAITB and WAITE bits are ignored and forced to 1 TPB cycle for a write operation; WAITB = 1 TPB cycle, WAITE = 0 TPB cycles for a read operation.

2: Address bits, A15 and A14, are not subject to automatic increment/decrement if configured as Chip Select CS2 and CS1.

3: These pins are active when MODE16 = 1 (16-bit mode).

REGISTER 22-1: RTCCON: RTC CONTROL REGISTER (CONTINUED)

bit 3 **RTCWREN:** RTC Value Registers Write Enable bit(4)
- 1 = RTC Value registers can be written to by the user
- 0 = RTC Value registers are locked out from being written to by the user

bit 2 **RTCSYNC:** RTCC Value Registers Read Synchronization bit
- 1 = RTC Value registers can change while reading, due to a rollover ripple that results in an invalid data read If the register is read twice and results in the same data, the data can be assumed to be valid
- 0 = RTC Value registers can be read without concern about a rollover ripple

bit 1 **HALFSEC:** Half-Second Status bit(5)
- 1 = Second half period of a second
- 0 = First half period of a second

bit 0 **RTCOE:** RTCC Output Enable bit
- 1 = RTCC clock output is enabled – clock presented onto an I/O
- 0 = RTCC clock output is disabled

Note 1: The ON bit is only writable when RTCWREN = 1.

2: When using the 1:1 PBCLK divisor, the user software should not read/write the peripheral's SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

3: Requires RTCOE = 1 (RTCCON<0>) for the output to be active.

4: The RTCWREN bit can be set only when the write sequence is enabled.

5: This bit is read-only. It is cleared to '0' on a write to the seconds bit fields (RTCTIME<14:8>).

Note: This register is reset only on a Power-on Reset (POR).

REGISTER 28-2: DEVCFG1: DEVICE CONFIGURATION WORD 1 (CONTINUED)

bit 15-14 **FCKSM<1:0>:** Clock Switching and Monitor Selection Configuration bits
- 1x = Clock switching is disabled, Fail-Safe Clock Monitor is disabled
- 01 = Clock switching is enabled, Fail-Safe Clock Monitor is disabled
- 00 = Clock switching is enabled, Fail-Safe Clock Monitor is enabled

bit 13-12 **FPBDIV<1:0>:** Peripheral Bus Clock Divisor Default Value bits
- 11 = PBCLK is SYSCLK divided by 8
- 10 = PBCLK is SYSCLK divided by 4
- 01 = PBCLK is SYSCLK divided by 2
- 00 = PBCLK is SYSCLK divided by 1

bit 11 **Reserved:** Write '1'

bit 10 **OSCIOFNC:** CLKO Enable Configuration bit
- 1 = CLKO output is disabled
- 0 = CLKO output signal active on the OSCO pin; Primary Oscillator must be disabled or configured for the External Clock mode (EC) for the CLKO to be active (POSCMOD<1:0> = 11 or 00)

bit 9-8 **POSCMOD<1:0>:** Primary Oscillator Configuration bits
- 11 = Primary Oscillator is disabled
- 10 = HS Oscillator mode is selected
- 01 = XT Oscillator mode is selected
- 00 = External Clock mode is selected

bit 7 **IESO:** Internal External Switchover bit
- 1 = Internal External Switchover mode is enabled (Two-Speed Start-up is enabled)
- 0 = Internal External Switchover mode is disabled (Two-Speed Start-up is disabled)

bit 6 **Reserved:** Write '1'

bit 5 **FSOSCEN:** Secondary Oscillator Enable bit
- 1 = Enable Secondary Oscillator
- 0 = Disable Secondary Oscillator

bit 4-3 **Reserved:** Write '1'

bit 2-0 **FNOSC<2:0>:** Oscillator Selection bits
- 111 = Fast RC Oscillator with divide-by-N (FRCDIV)
- 110 = FRCDIV16 Fast RC Oscillator with fixed divide-by-16 postscaler
- 101 = Low-Power RC Oscillator (LPRC)
- 100 = Secondary Oscillator (SOSC)
- 011 = Primary Oscillator (POSC) with PLL module (XT+PLL, HS+PLL, EC+PLL)
- 010 = Primary Oscillator (XT, HS, EC)(1)
- 001 = Fast RC Oscillator with divide-by-N with PLL module (FRCDIV+PLL)
- 000 = Fast RC Oscillator (FRC)

Note 1: Do not disable the POSC (POSCMOD = 11) when using this oscillator source.

30.6 MPLAB X SIM Software Simulator

The MPLAB X SIM Software Simulator allows code development in a PC-hosted environment by simulating the PIC MCUs and dsPIC DSCs on an instruction level. On any given instruction, the data areas can be examined or modified and stimuli can be applied from a comprehensive stimulus controller. Registers can be logged to files for further run-time analysis. The trace buffer and logic analyzer display extend the power of the simulator to record and track program execution, actions on I/O, most peripherals and internal registers.

The MPLAB X SIM Software Simulator fully supports symbolic debugging using the MPLAB XC Compilers, and the MPASM and MPLAB Assemblers. The software simulator offers the flexibility to develop and debug code outside of the hardware laboratory environment, making it an excellent, economical software development tool.

30.7 MPLAB REAL ICE In-Circuit Emulator System

The MPLAB REAL ICE In-Circuit Emulator System is Microchip's next generation high-speed emulator for Microchip Flash DSC and MCU devices. It debugs and programs all 8, 16 and 32-bit MCU, and DSC devices with the easy-to-use, powerful graphical user interface of the MPLAB X IDE.

The emulator is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with either a connector compatible with in-circuit debugger systems (RJ-11) or with the new high-speed, noise tolerant, Low-Voltage Differential Signal (LVDS) interconnection (CAT5).

The emulator is field upgradable through future firmware downloads in MPLAB X IDE. MPLAB REAL ICE offers significant advantages over competitive emulators including full-speed emulation, run-time variable watches, trace analysis, complex breakpoints, logic probes, a ruggedized probe interface and long (up to three meters) interconnection cables.

30.8 MPLAB ICD 3 In-Circuit Debugger System

The MPLAB ICD 3 In-Circuit Debugger System is Microchip's most cost-effective, high-speed hardware debugger/programmer for Microchip Flash DSC and MCU devices. It debugs and programs PIC Flash microcontrollers and dsPIC DSCs with the powerful, yet easy-to-use graphical user interface of the MPLAB IDE.

The MPLAB ICD 3 In-Circuit Debugger probe is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with a connector compatible with the MPLAB ICD 2 or MPLAB REAL ICE systems (RJ-11). MPLAB ICD 3 supports all MPLAB ICD 2 headers.

30.9 PICkit 3 In-Circuit Debugger/ Programmer

The MPLAB PICkit 3 allows debugging and programming of PIC and dsPIC Flash microcontrollers at a most affordable price point using the powerful graphical user interface of the MPLAB IDE. The MPLAB PICkit 3 is connected to the design engineer's PC using a full-speed USB interface and can be connected to the target via a Microchip debug (RJ-11) connector (compatible with MPLAB ICD 3 and MPLAB REAL ICE). The connector uses two device I/O pins and the Reset line to implement in-circuit debugging and In-Circuit Serial Programming™ (ICSP™).

30.10 MPLAB PM3 Device Programmer

The MPLAB PM3 Device Programmer is a universal, CE compliant device programmer with programmable voltage verification at V_{DDMIN} and V_{DDMAX} for maximum reliability. It features a large LCD display (128 x 64) for menus and error messages, and a modular, detachable socket assembly to support various package types. The ICSP cable assembly is included as a standard item. In Stand-Alone mode, the MPLAB PM3 Device Programmer can read, verify and program PIC devices without a PC connection. It can also set code protection in this mode. The MPLAB PM3 connects to the host PC via an RS-232 or USB cable. The MPLAB PM3 has high-speed communications and optimized algorithms for quick programming of large memory devices, and incorporates an MMC card for file storage and data applications.

TABLE 31-8: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symb.**	**Characteristics**	**Min.**	**Typ.(1)**	**Max.**	**Units**	**Conditions**
		Input Low Voltage					
DI10	VIL	I/O Pins with PMP	VSS	—	0.15 VDD	V	
		I/O Pins	VSS	—	0.2 VDD	V	
DI18		SDAx, SCLx	VSS	—	0.3 VDD	V	SMBus disabled **(Note 4)**
DI19		SDAx, SCLx	VSS	—	0.8	V	SMBus enabled **(Note 4)**
		Input High Voltage					
DI20	VIH	I/O Pins not 5V-tolerant**(5)**	0.65 VDD	—	VDD	V	**(Note 4,6)**
		I/O Pins 5V-tolerant with PMP**(5)**	0.25 VDD + 0.8V	—	5.5	V	**(Note 4,6)**
		I/O Pins 5V-tolerant**(5)**	0.65 VDD	—	5.5	V	
DI28		SDAx, SCLx	0.65 VDD	—	5.5	V	SMBus disabled **(Note 4,6)**
DI29		SDAx, SCLx	2.1	—	5.5	V	SMBus enabled, 2.3V ≤ VPIN ≤ 5.5 **(Note 4,6)**
DI30	ICNPU	**Change Notification Pull-up Current**	—	—	-50	µA	VDD = 3.3V, VPIN = VSS **(Note 3,6)**
DI31	ICNPD	**Change Notification Pull-down Current(4)**	—	50	—	µA	VDD = 3.3V, VPIN = VDD

Note 1: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

2: The leakage current on the $\overline{\text{MCLR}}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

4: This parameter is characterized, but not tested in manufacturing.

5: See the **"Device Pin Tables"** section for the 5V tolerant pins.

6: The VIH specifications are only in relation to externally applied inputs, and not with respect to the user-selectable internal pull-ups. External open drain input signals utilizing the internal pull-ups of the PIC32 device are guaranteed to be recognized only as a logic "high" internally to the PIC32 device, provided that the external load does not exceed the minimum value of ICNPU. For External "input" logic inputs that require a pull-up source, to guarantee the minimum VIH of those components, it is recommended to use an external pull-up resistor rather than the internal pull-ups of the PIC32 device.

7: VIL source < (VSS - 0.3). Characterized but not tested.

8: VIH source > (VDD + 0.3) for non-5V tolerant pins only.

9: Digital 5V tolerant pins do not have an internal high side diode to VDD, and therefore, cannot tolerate any "positive" input injection current.

10: Injection currents > | 0 | can affect the ADC results by approximately 4 to 6 counts (i.e., VIH Source > (VDD + 0.3) or VIL source < (VSS - 0.3)).

11: Any number and/or combination of I/O pins not excluded under IICL or IICH conditions are permitted provided the "absolute instantaneous" sum of the input injection currents from all pins do not exceed the specified limit. If **Note 7**, IICL = (((Vss - 0.3) - VIL source) / Rs). If **Note 8**, IICH = ((IICH source - (VDD + 0.3)) / RS). RS = Resistance between input source voltage and device pin. If (VSS - 0.3) ≤ VSOURCE ≤ (VDD + 0.3), injection current = 0.

TABLE 31-10: ELECTRICAL CHARACTERISTICS: BOR

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics**	**Min.(1)**	**Typical**	**Max.**	**Units**	**Conditions**
BO10	VBOR	BOR Event on VDD transition high-to-low	2.0	—	2.3	V	—

Note 1: Parameters are for design guidance only and are not tested in manufacturing.

TABLE 31-11: ELECTRICAL CHARACTERISTICS: HVD

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.(1)	**Symbol**	**Characteristics**	**Min.**	**Typical**	**Max.**	**Units**	**Conditions**
HV10	VHVD	High Voltage Detect on VCAP pin	—	2.5	—	V	—

Note 1: Parameters are for design guidance only and are not tested in manufacturing.

31.2 AC Characteristics and Timing Parameters

The information contained in this section defines PIC32MX330/350/370/430/450/470 AC characteristics and timing parameters.

FIGURE 31-1: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS

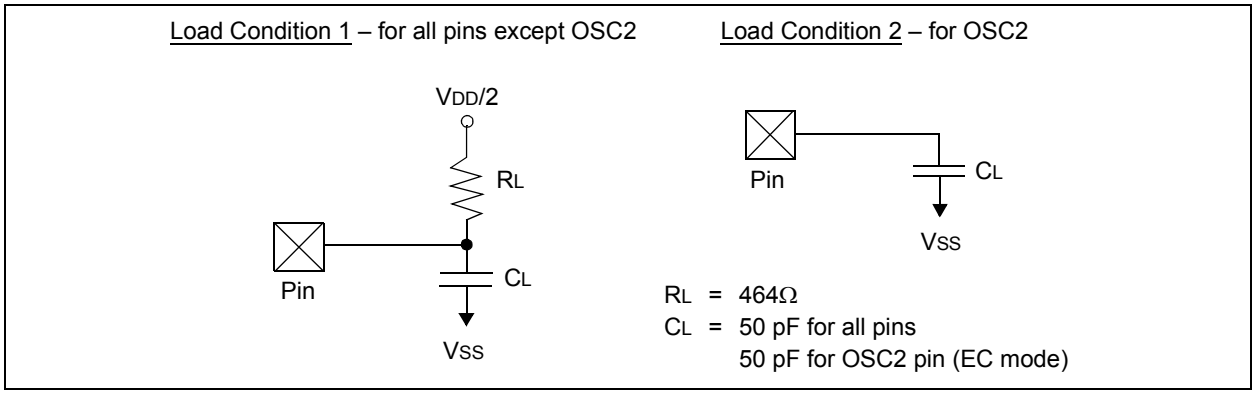


TABLE 31-17: CAPACITIVE LOADING REQUIREMENTS ON OUTPUT PINS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical(1)**	**Max.**	**Units**	**Conditions**
DO50	COSCO	OSC2 pin	—	—	15	pF	In XT and HS modes when an external crystal is used to drive OSC1
DO56	CIO	All I/O pins and OSC2	—	—	50	pF	EC mode
DO58	CB	SCLx, SDAx	—	—	400	pF	In I^2C mode

Note 1: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

FIGURE 31-2: EXTERNAL CLOCK TIMING

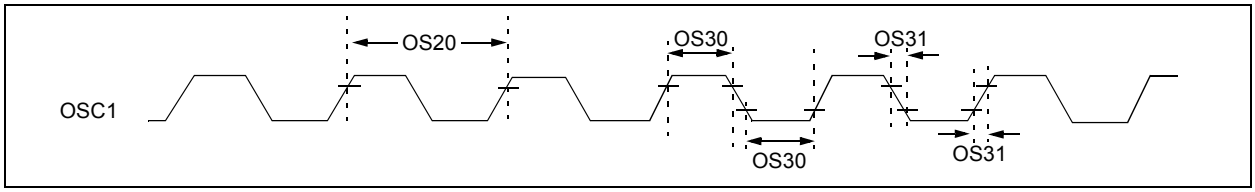


TABLE 31-33: I2Cx BUS DATA TIMING REQUIREMENTS (MASTER MODE)

AC CHARACTERISTICS				Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp			
Param. No.	**Symbol**	**Characteristics**		**Min.(1)**	**Max.**	**Units**	**Conditions**
IM10	TLO:SCL	Clock Low Time	100 kHz mode	TPB * (BRG + 2)	—	µs	—
			400 kHz mode	TPB * (BRG + 2)	—	µs	—
			1 MHz mode **(Note 2)**	TPB * (BRG + 2)	—	µs	—
IM11	THI:SCL	Clock High Time	100 kHz mode	TPB * (BRG + 2)	—	µs	—
			400 kHz mode	TPB * (BRG + 2)	—	µs	—
			1 MHz mode **(Note 2)**	TPB * (BRG + 2)	—	µs	—
IM20	TF:SCL	SDAx and SCLx Fall Time	100 kHz mode	—	300	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode **(Note 2)**	—	100	ns	
IM21	TR:SCL	SDAx and SCLx Rise Time	100 kHz mode	—	1000	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode **(Note 2)**	—	300	ns	
IM25	TSU:DAT	Data Input Setup Time	100 kHz mode	250	—	ns	—
			400 kHz mode	100	—	ns	
			1 MHz mode **(Note 2)**	100	—	ns	
IM26	THD:DAT	Data Input Hold Time	100 kHz mode	0	—	µs	—
			400 kHz mode	0	0.9	µs	
			1 MHz mode **(Note 2)**	0	0.3	µs	
IM30	TSU:STA	Start Condition Setup Time	100 kHz mode	TPB * (BRG + 2)	—	µs	Only relevant for Repeated Start condition
			400 kHz mode	TPB * (BRG + 2)	—	µs	
			1 MHz mode **(Note 2)**	TPB * (BRG + 2)	—	µs	
IM31	THD:STA	Start Condition Hold Time	100 kHz mode	TPB * (BRG + 2)	—	µs	After this period, the first clock pulse is generated
			400 kHz mode	TPB * (BRG + 2)	—	µs	
			1 MHz mode **(Note 2)**	TPB * (BRG + 2)	—	µs	
IM33	TSU:STO	Stop Condition Setup Time	100 kHz mode	TPB * (BRG + 2)	—	µs	—
			400 kHz mode	TPB * (BRG + 2)	—	µs	
			1 MHz mode **(Note 2)**	TPB * (BRG + 2)	—	µs	

Note 1: BRG is the value of the I^2C Baud Rate Generator.

2: Maximum pin capacitance = 10 pF for all I2Cx pins (for 1 MHz mode only).

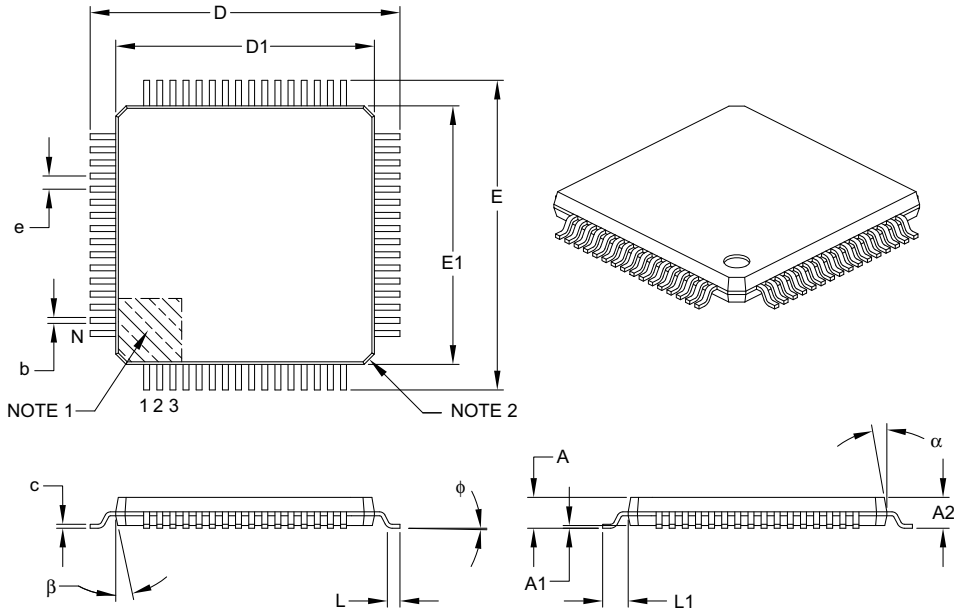
3: The typical value for this parameter is 104 ns.

33.2 Package Details

The following sections give the technical details of the packages.

64-Lead Plastic Thin Quad Flatpack (PT) – 10x10x1 mm Body, 2.00 mm [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N		64	
Lead Pitch	e		0.50 BSC	
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	–	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1		1.00 REF	
Foot Angle	ϕ	0°	3.5°	7°
Overall Width	E		12.00 BSC	
Overall Length	D		12.00 BSC	
Molded Package Width	E1		10.00 BSC	
Molded Package Length	D1		10.00 BSC	
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.17	0.22	0.27
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

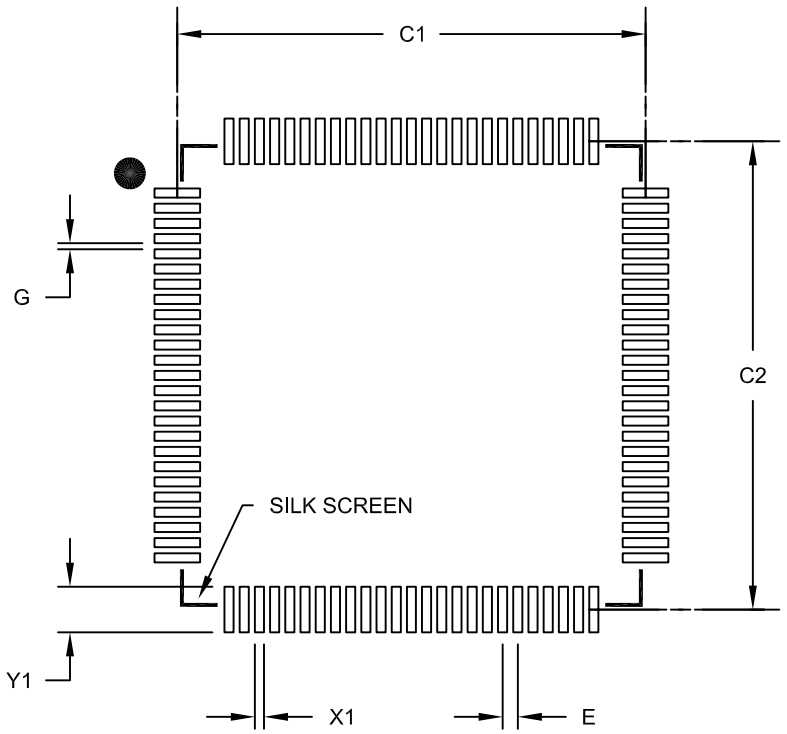
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-085B

100-Lead Plastic Thin Quad Flatpack (PF) - 14x14x1 mm Body 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.50 BSC	
Contact Pad Spacing	C1		15.40	
Contact Pad Spacing	C2		15.40	
Contact Pad Width (X100)	X1			0.30
Contact Pad Length (X100)	Y1			1.50
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2110B